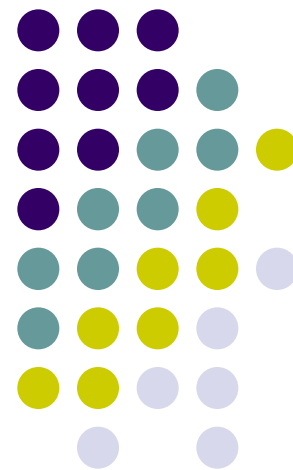




Your Reliable Partner

Viking Tech Corp.

investor conference 2026



Company Profile

- Establishment : October 1997
- Capital : NTD 11.73B
- OTC Market : Y2011
- Headquarter: Hsinchu, Taiwan
- Factory Location:

Hsinchu



Hsinchu (Factory II)



Kaohsiung

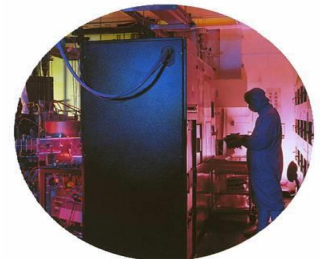
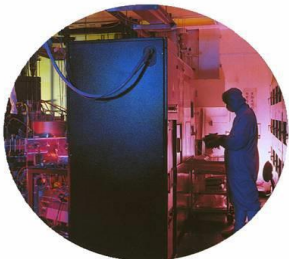
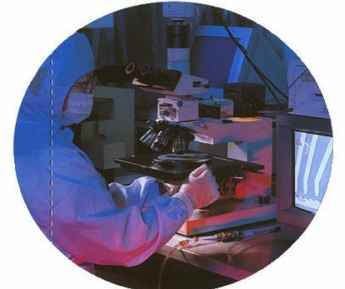


Wuxi, China



Core Technology & Main Products

Thin Film / Thick Film Technology, Metal Foil, RF



Product Introduction



Resistor

- Precision Thin Film
- General Thick Film
- High Ohm
- High Voltage
- Miniature Size
- Metal Foil
- Power Resistor
- Automotive Grade
- Anti-Sulfurated
- Ultra Low ohm (Metal Strip)
- Array Resistor
- Special Functional Resistor

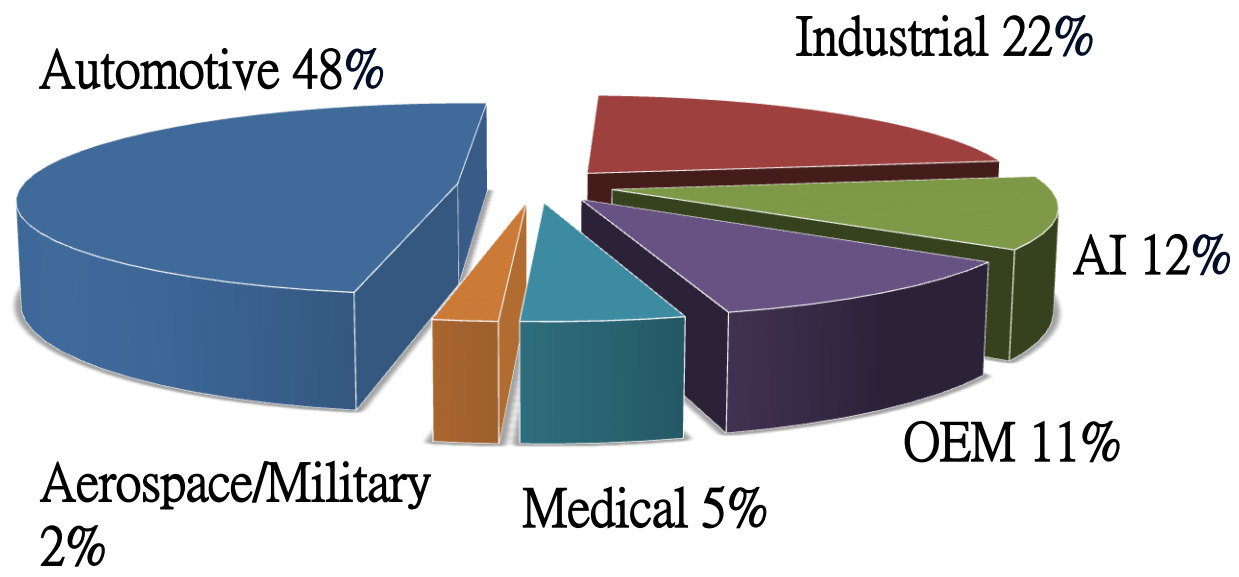
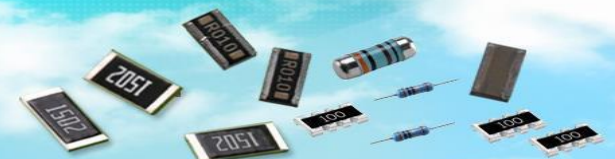
Inductor

- High Frequency Thin Film chip Inductor
- Wire wound chip Inductor
- Multilayer chip inductor
- Miniature Size Power Inductor
- SMD Power Inductor
- EMI Filter

Capacitor

- MLCC
- High Q and Low ESR
- Ultra High Q and Low ESR

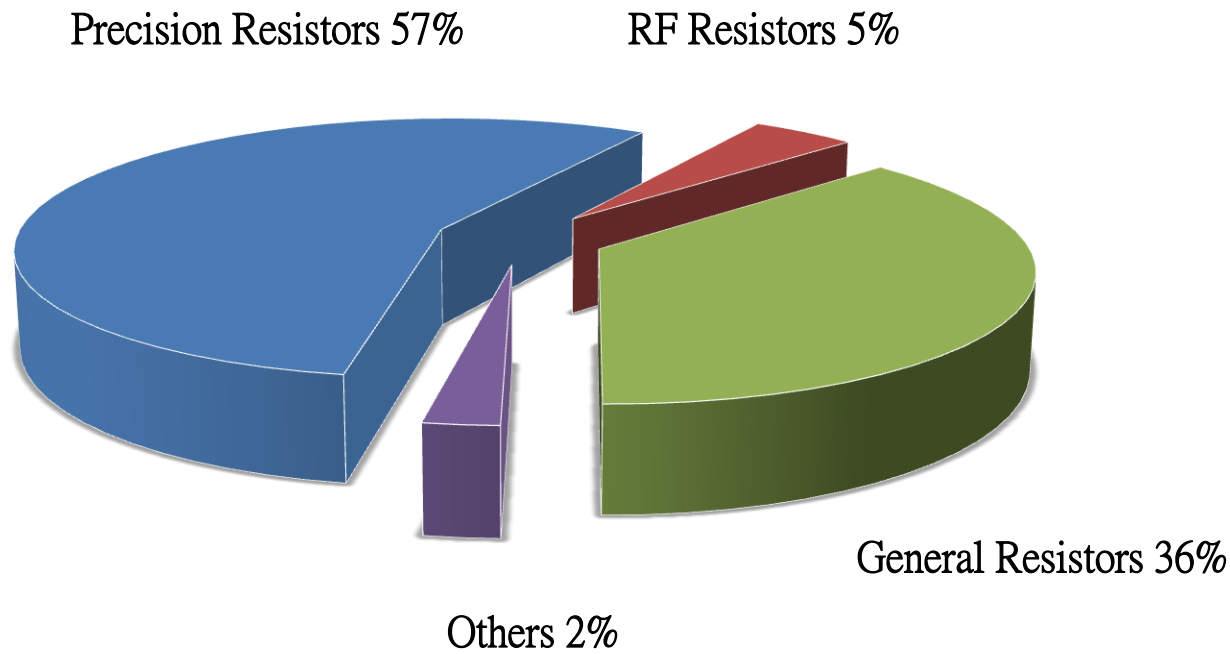
Market Segmentation



AI: Sever, GPU, SWITCHING, DATACENTER, SEVER POWER
Industrial : Smart Meter, Test Measurement equipment, Energy, Power and Controller, Robot
Medical : AED, Personal Health Care, Blood Glucose Measurement, ECG Monitor...
Automotive : BMS, ADAS, ESU, Engine Control System, Charging Point, Car Key, Infotainment,
Aerospace/Military : Communication system, Satellite

Main Product Share

2026.Q1



Our Advantages



Advanced, Experienced
Component
Technology



Flexible Extension
Sufficient Capacity



Wide Range Products,
Excellent Technical
Support



Well-Organized, ERP
System. IATF16949,
Automotive Grade



Quick Turnaround
Time and Response

CP↑

On Public
Company
Superior
Management
High Yield
Cost Effective



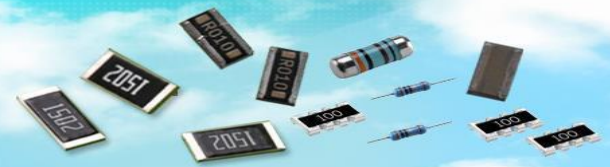
Short Lead Time and
Free Sample Support



Extensive RD Team,
Miniature Size, High
Power, New Product
Development



Customers



Industrial / Medical

Automotives

PEPPERL+FUCHS
Great Wall 长城
Danfoss
MW MEAN WELL
ABB
SMA
UNI-T
Roche
ADVANTECH
mindray 迈瑞
Johnson & Johnson
Rossmax[®] medical
国家电网 STATE GRID
南瑞集团公司 NARI GROUP CORPORATION
LARSEN & TOUBRO
It's all about Imagineering
Agilent Technologies

BOSCH
HELLA
MARELLI
KIA
MARQUARDT
HYUNDAI MOBIS
CASCO
LOGOS

Aerospace / Military

AAI
AeroVision Avionics, Inc.
利翔航太電子股份有限公司

被動元件、主動服務！

CONSOLIDATED STATEMENTS OF COMPREHENSIVE INCOME(1)



Amount in NT\$ Thousands

	2023		2024		2025		2026. 1-3	
	Amount	%						
Operating revenue	2, 553, 243	100. 0	2, 581, 140	100. 0	2, 675, 360	100. 0	727, 980	100. 0
Operating costs	(1, 845, 306)	(72. 3)	(1, 913, 189)	(74. 1)	(1, 998, 731)	(74. 7)	(520, 091)	(71. 4)
Gross profit	707, 937	27. 7	667, 951	25. 9	676, 629	25. 3	207, 889	28. 6
operating expenses	(399, 343)	(15. 6)	(421, 653)	(16. 3)	(416, 931)	(15. 6)	(111, 461)	(15. 3)
Operating profit	308, 594	12. 2	246, 298	9. 6	259, 698	9. 7	96, 428	13. 2
Non-operating income and expenses	16, 753	0. 7	52, 816	2. 0	20, 190	0. 8	21, 966	3. 0
Profitbefore income tax	325, 347	12. 7	299, 114	11. 6	279, 888	10. 5	118, 394	16. 3
Income tax expense	(63, 151)	(2. 5)	(54, 536)	(2. 1)	(58, 088)	(2. 2)	(29, 414)	(4. 0)
Profit for the year	262, 196	10. 3	244, 578	9. 5	221, 800	8. 3	88, 980	12. 2
Profit for the year(Owners of the parent)	261, 813	10. 3	242, 120	9. 4	218, 179	8. 2	87, 930	12. 1
EPS(NT\$ Dollar)	2. 23		2. 06		1. 86		0. 75	

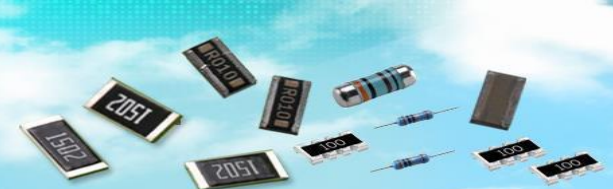
CONSOLIDATED STATEMENTS OF COMPREHENSIVE INCOME(2)



Amount in NT\$ Thousands

	2026Q1		2025Q4		Q-Q Change(%)	2025Q1		Y-Y Change(%)
	Amount	%	Amount	%		Amount	%	
Operating revenue	727,980	100.0	656,713	100.0	10.9	618,995	100.0	17.6
Operating costs	(520,091)	(71.4)	(503,682)	(76.7)	3.3	(454,583)	(73.4)	14.4
Gross profit	207,889	28.6	153,031	23.3	35.8	164,412	26.6	26.4
operating expenses	(111,461)	(15.3)	(105,722)	(16.1)	5.4	(103,931)	(16.8)	7.2
Operating profit	96,428	13.2	47,309	7.2	103.8	60,481	9.8	59.4
Non-operating income and expenses	21,966	2.9	34,904	5.3	37.1	20,503	3.3	(7.1)
Profitbefore income tax	118,394	16.3	82,213	12.5	44.0	80,984	13.1	46.2
Income tax expense	(29,414)	(4.0)	(4,925)	(0.7)	497.2	(17,068)	(2.8)	72.3
Profit for the year	88,980	12.2	77,288	11.8	(15.1)	63,916	10.3	39.2
Profit for the year(Owners of the parent)	87,930	12.1	76,347	11.6	(15.2)	63,259	10.2	39.0
EPS(NT\$ Dollar)	0.75		0.65			0.54		

CONSOLIDATED BALANCE SHEETS(1)



	Amount in NT\$ Thousands							
	2023		2024		2025		2026. 3. 31	
	Amount	%	Amount	%	Amount	%	Amount	%
Cash and cash equivalents	792,389	20.6	681,702	17.7	637,438	16.6	585,209	15.2
Notes & Accounts Receivable	507,039	13.2	496,243	12.9	568,613	14.8	629,645	16.4
Inventory	795,666	20.7	696,023	18.1	747,320	19.4	840,925	21.8
Property, plant and equipment	1,278,070	33.2	1,226,708	31.9	1,193,298	31.0	1,179,192	30.6
Total assets	3,850,385	100.0	3,953,387	102.7	4,096,171	106.4	4,315,394	112.1
Short-term borrowings	0	0.0	0	0.0	0	0.0	0	0.0
Notes & Accounts Payable	192,479	5.0	175,675	4.6	219,759	5.7	304,537	7.9
current liabilities	484,325	12.6	493,086	12.8	567,608	14.7	690,966	17.9
non-current liabilities	75,331	2.0	50,081	1.3	39,128	1.0	34,233	0.9
Total Liabilities	559,656	14.5	543,167	14.1	606,736	15.8	725,199	18.8
Total equity	3,290,729	85.5	3,410,220	88.6	3,489,435	90.6	3,590,195	93.2

CONSOLIDATED BALANCE SHEETS(2)



Amount in NT\$ Thousands

	2026. 3. 31		2025. 12. 31		Q-Q	2025. 3. 31		Y-Y
	Amount	%	Amount	%	Change(%)	Amount	%	Change(%)
Cash and cash equivalents	585,209	13.6	637,438	15.6	(8.2)	593,865	14.7	(1.5)
Notes & Accounts Receivable	629,645	14.6	568,613	13.9	10.7	511,134	12.7	23.2
Inventory	840,925	19.5	747,320	18.2	12.5	666,480	16.5	26.2
Property, plant and equipment	1,179,192	27.3	1,193,298	29.1	(1.2)	1,206,365	29.9	(2.3)
Total assets	4,315,394	100.0	4,096,171	100.0	5.4	4,029,369	100.0	7.1
Short-term borrowings	0	0.0	0	0.0		0	0.0	
Notes & Accounts Payable	304,537	7.1	219,759	5.4	38.6	182,664	4.5	66.7
current liabilities	690,966	16.0	567,608	13.9	21.7	499,588	12.4	38.3
non-current liabilities	34,233	0.8	39,128	1.0	(12.5)	45,427	1.1	(24.6)
Total Liabilities	725,199	16.8	606,736	14.8	19.5	545,015	13.5	33.1
Total equity	3,590,195	83.2	3,489,435	85.2	2.9	3,484,354	86.5	3.0

Future development strategies



Focusing on the development of core technologies, improving process capabilities, and meet the requirements of third-generation of semiconductor specifications (high voltage, high frequency, high power and high temperature).

Consistently develop and aiming on Automotive/ Medical/ Industrial equipment market.

Develop and market high-end electronic components to meet the application fields of smart products.

Improve customer satisfaction and supplier relationships.



Q&A



Thank you !

